| ASSOCIATION CONNECTING<br>ELECTRONICS INDUSTRIES® INDUSTRIES®   | burn, Illinois. Al                                     | l rights reserved un<br>tions. | ider both    | his docume<br>vel parts, tl   | ent is a declarat<br>he declaration e                      | ion of the sub<br>encompasses | bstances<br>all lower | within the manufactur<br>r level materials for wl | er listed i<br>hich the n | tem. Note: in<br>nanufacturer | f the item is an as<br>has engineering | sembly with lower responsibility. |
|---|--|--------------------------------|--------------|---|--|-------------------------------|-----------------------|---|---------------------------|-------------------------------|--|-----------------------------------|
| 21.1 IPC Web Site for Information on IPC-1752 Standard Form Typ<br>http://www.ipc.org/IPC-175x Distribute |  |                                |              | * Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Materials and |  |                               |                       |   | als and M                 | lfg Informati                 | on                                     |                                   |
| Supplier Information  |  |                                |              |   |  |                               |                       |   |                           |                               |  |                                   |
| Company name* Company unique ID   |  |                                |              | Unique ID Authority   |  |                               |                       |   | Response Date*            |                               |  |                                   |
| nsemi   |  |                                |              |   |  |                               |                       |   | 2024-05-21                |                               |  |                                   |
| Contact Name  | Title - Contact  |                                |              | ]   | Phone - Contact*   |                               |                       |   | Email - Contact*          |                               |  |                                   |
| Product-Env-Stewards  | duct-Env-Stewards Product Enviro Compliance            |                                |              | NA  |  |                               |                       | Product-Env-Stewards@onsemi.com                   |                           |                               |  |                                   |
| Authorized Representative* Title - Representative   |  |                                |              | Phone - Representative*   |  |                               |                       | Email - Representative*                           |                           |                               |  |                                   |
| Product-Env-Stewards Product Enviro Compliance  |  |                                |              | NA  |  |                               |                       | Product-Env-Stewards@onsemi.com                   |                           |                               |  |                                   |
| Requester Item Number Mfr Ite   | m Number   | Mfr Item Name                  |              |   | Effective Date   | Version                       | N                     | Manufacturing Site                                |                           | Weight*                       | UOM                                    | Unit Type                         |
| MC140   | MC14093BDR2G LOG CMOS SCH                              |                                | MITT TRG QUA | ٨D  | 2024-05-21   | PH1                           |                       |   | 122.04                    | mg                            | Each                                   |                                   |
| Manufacturing Proccess Information  |  |                                |              |   | •  |                               |                       |   |                           |                               |  | ·                                 |
| Terminal Plating / Grid Array Material  | Plating / Grid Array Material Terminal Base Alloy J-ST |                                |              | Rating  | Peak Process Body Temperature Max Time at Peak Temperature |                               |                       |   |                           | ture Numb                     | er of Reflow Cyd                       | eles                              |
| Matte Tin (Sn) - annealed CU Alloy 1  |  |                                |              |   | 260  |                               | С                     | 30  | secon                     | nds 3                         |  |                                   |
| Comments  |  |                                |              |   |  |                               |                       |   |                           |                               |  |                                   |
| level 1 - maximum time at peak temperature during s   | oldering is 10-30                                      | seconds                        |              |   |  |                               |                       |   |                           |                               |  |                                   |
| For more information regarding material compositio  | n please refer to                                      | page 3                         |              |   |  |                               |                       |   |                           |                               |  |                                   |

| RoHS Material Composition Declaration  |  |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |  |
|--|--|--|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP). |  |   |   |   |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>y others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the   | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and cc<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa  | Supplier Acceptance  | * Accepted  |   |   |  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per   | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU   |  |   |   |   |  |  |  |  |  |  |
| Declaration Signature  |  |  |   |   |   |  |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester  | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska  | Le   |   |   |   |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| select a RoHS exemption, if appli                          | cable [E] enter the weigh |                 |          | ance category (JIG or Requester) or enter a<br>[F] Optionally enter the positive (+) and n |                  |        |         |                 |
|--|---------------------------|-----------------|----------|--|------------------|--------|---------|-----------------|
| sigma range of distribution unless<br>Homogeneous Material | Weight                    | Unit of Measure | Level    | Substance  | CAS              | Exempt | Weight  | Unit of Measure |
| Die  | 0.98                      | mg              | Supplier | Silicon (Si)   | 7440-21-3        |        | 0.98    | mg              |
| Die Attach   | 4.44                      | mg              | Supplier | Silver (Ag)  | 7440-22-4        |        | 3.33    | mg              |
|  |                           |                 | Supplier | Epoxy resins   | 129915-35-1      |        | 1.11    | mg              |
| Lead Frame 69  | 69.62                     | mg              | Supplier | Silver (Ag)  | 7440-22-4        |        | 0.7658  | mg              |
|  |                           |                 | Supplier | Zinc (Zn)  | 7440-66-6        |        | 0.1392  | mg              |
|  |                           |                 | Supplier | Iron (Fe)  | 7439-89-6        |        | 1.8101  | mg              |
|  |                           |                 | Supplier | Copper (Cu)  | 7440-50-8        |        | 66.9048 | mg              |
| Mold Compound-Black  | 43.43                     | mg              |          | Epoxy resin  | proprietary data |        | 2.1715  | mg              |
|  |                           |                 |          | Phenolic Resin   | Proprietary Data |        | 2.1715  | mg              |
|  |                           |                 | Supplier | Ortho Cresol Novolac Resin   | 29690-82-2       |        | 0.8686  | mg              |
|  |                           |                 | Supplier | Carbon Black (C)   | 1333-86-4        |        | 0.2172  | mg              |
|  |                           |                 | Supplier | Fused Silica (SiO2)  | 60676-86-0       |        | 38.0013 | mg              |
| Plating  | 3.27                      | mg              | Supplier | Tin (Sn)   | 7440-31-5        |        | 3.27    | mg              |
| Wire Bond - Cu   | 0.3                       | mg              | Supplier | Copper (Cu)  | 7440-50-8        |        | 0.3     | mg              |